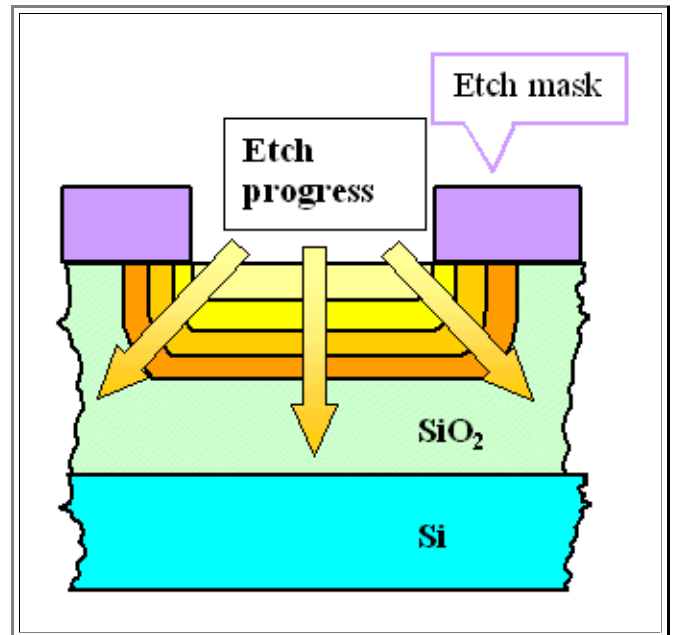


6.5.3 Summary to: Etching Techniques

Chemical etching:

Relatively simple, with luck extremely selective, relatively fast, but:

- Material removal always isotropic (see figure) and thus enlarging features and thus not applicable to "micro" or better "nano" structuring
- Might be extremely dangerous (corrosive, poisonous, inflammable, explosive, ...) and often hard to recycle / dispose off.



Plasma Etching:

Simple in principle (see figure) quite complex and expensive in praxis.

- Given the right plasma (not easy to find; plasma chemistry counts among the "black arts"), the etching can be completely anisotropic and sufficiently selective.
- Innumerable variants exist and new methods are coming up all the time. Definitely one of the key technologies for micro / nano technology.

